### **Product / Process Change Notification**



#### N° 2020-157-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

# Introduction of G700LTD Mould Compound and AU wire in PG-VQFN-56-900 products at Carsem S.

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 01. February 2021.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Wolfgang Eder Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg Commercial Register: München HRB 126492

## **Product / Process Change Notification**



#### N° 2020-157-A

Products affected: Please refer to attached affected product list 1\_cip20016\_A

### Detailed Change Information:

Subject:	Introduction of G700LTD Mould Compound and AU wire in PG-VQFN- 56-900 products at Carsem S				
Reason:	Product reliability improvement to support DCDC business grow				
Description:	<u>Old</u>	New			
Assembly and Final Test location	<ul> <li>Carsem Semiconductor (Suzhou) Co. Ltd China (Assembly)</li> <li>ASE Electronics (M) Sdn. Bhd, Penang (Test)</li> </ul>	<ul> <li>Carsem Semiconductor (Suzhou) Co. Ltd , China (Assembly)</li> <li>ASE Electronics (M) Sdn. Bhd, Penang (Test)</li> <li>Carsem (S) Sdn Bhd, Ipoh (Assembly and Test)</li> </ul>			
Marking on device	<ul> <li>Carsem Semiconductor (Suzhou) Co. Ltd China (Assembly)</li> <li>ASE Electronics (M) Sdn. Bhd, Penang (Test)</li> </ul>	<ul> <li>Carsem Semiconductor (Suzhou) Co. Ltd China (Assembly)</li> <li>ASE Electronics (M) Sdn. Bhd, Penang (Test)</li> </ul>			
	PIN 1 ASSEMBLY SITE CODE XXXXX (fing mode - 4 dgls SM code)	PIN 1 ASSEMBLY SITE CODE XXXXX (Per Morking Spec.) XXXXX (Per Morking Spec.) XXXXX (Per Morking Spec.) (Per Morking Spec.)			
		Carsem (S) Sdn Bhd, Ipoh (Assembly and Test)     PIN1 INDICATOR, 0.30mm DIAMETER     PART NUMBER     "G" MEANS GOLD WIRE     DMX CODE 18x8 PIXEL     DATE CODE (YWW)     LEAD FREE (P)     XXXX PRODUCTION CODE     ASSEMBLY SITE     CODE (C)			
Bonding Wire	<ul> <li>Cu PDSOFT ( CARSEM_SZ)</li> </ul>	<ul> <li>Cu PDSOFT ( CARSEM_SZ)</li> <li>AU ( CARSEM S)</li> </ul>			
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## Product / Process Change Notification

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N° 2020-157-A				
Mould Compound	G770HCD ( CARSEM_SZ)	<ul> <li>G770HCD (CARSEM_SZ)</li> <li>G700LTD (CARSEM_S)</li> </ul>		
Package Outline Drawing	Please refer to 3_cip20157_a			
<ul> <li>Product Identification:</li> </ul>	Internal traceability via Baunumber, Lotnumber, date code and marking on device External traceability via the marking on device			
Impact of Change:	<ul> <li>NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.</li> <li>NO change of electrical parameters in the datasheet.</li> <li>NO change in quality and device processability at customer end.</li> <li>Assembly processes are optimized to meet product performance according to already applied Infineon specification.</li> <li>Update of package outline drawing in the datasheet.</li> </ul>			
<ul> <li>Attachments:</li> </ul>	1_cip20157_a Affected product list 2_cip20157_a Qualification report 3_cip20157_a Customer Information (detailed change desc package outline draw	cription of product identification and		

#### ► Time Schedule:

<ul> <li>First samples available:</li> </ul>	2020-12-31
Full Qualification report	2020-11-16
Intended start of delivery:	2021-03-31 or earlier based on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

#### PCN N° 2020-157-A Introduction of G700LTD Mould Compound and AU wire in PG-VQFN-56-900 products at Carsem S



Sales name	SP number	OPN	Package
IR35217MTRPBF	SP001525802	IR35217MTRPBF	PG-VQFN-56-9
IR35217MAM02TRP	SP001676542	IR35217MAM02TRP	PG-VQFN-56-9
IR35217MAM01TRP	SP001676550	IR35217MAM01TRP	PG-VQFN-56-9
IR35217-PMA010	SP002866998	IR35217-PMA010AUMA1	PG-VQFN-56-9
IR35217-PMB010	SP002867000	IR35217-PMB010AUMA1	PG-VQFN-56-9
IR35217-PMC010	SP002867002	IR35217-PMC010AUMA1	PG-VQFN-56-9
IR35217-PME010	SP004177708	IR35217-PME010AUMA1	PG-VQFN-56-9
IR35217-PMH010	SP004866436	IR35217-PMH010AUMA1	PG-VQFN-56-9
IR35217-PMK010	SP004866438	IR35217-PMK010AUMA1	PG-VQFN-56-9
IR35217-PMJ010	SP004866440	IR35217-PMJ010AUMA1	PG-VQFN-56-9
IR35217-PML010	SP005355240	IR35217-PML010AUMA1	PG-VQFN-56-9
IR35217-PMP010	SP005355241	IR35217-PMP010AUMA1	PG-VQFN-56-9
IR35217-PMQ010	SP005355242	IR35217-PMQ010AUMA1	PG-VQFN-56-9